



Surface Mount Schottky Rectifier

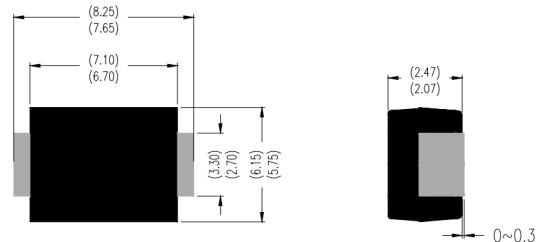
Features

- Guardring for overvoltage protection
- Low forward voltage drop, Low power losses
- High forward surge capability
- AEC-Q101 qualified
- High frequency operation
- Solder dip 260 °C max. 10 s, per JESD 22-B106

Typical Applications

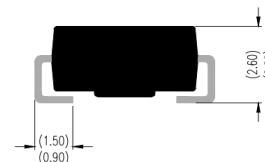
For use in low voltage high frequency inverters, freewheeling, DC/DC converters, and polarity protection applications.

DO-214AB (SMC)



Mechanical Data

- **Package:** DO-214AB (SMC)
Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** Color band denotes the cathode end



Unit : inch(mm)



■ Maximum Ratings ($T_a=25^\circ\text{C}$ Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	SL56C
Repetitive Peak Reverse Voltage	V_{RRM}	V	65
Average Rectified Output Current @60Hz sine wave, Resistance load, T_a (FIG.1)	I_o	A	5.0
Forward Surge Current (Non-repetitive) @ 60Hz Half-sine wave, 1 cycle, $T_a=25^\circ\text{C}$	I_{FSM}	A	120
Storage Temperature	T_{stg}	$^\circ\text{C}$	-55 ~+150
Junction Temperature	T_j	$^\circ\text{C}$	-55 ~+150

■ Electrical Characteristics ($T_a=25^\circ\text{C}$ Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	SL56C
Maximum instantaneous forward voltage drop per diode	V_F	V	$I_{FM}=5.0\text{A}$	0.52
Maximum DC reverse current at rated DC blocking voltage per diode	I_R	mA	$T_a=25^\circ\text{C}$	0.1



■ Thermal Characteristics ($T_a=25^\circ\text{C}$ Unless otherwise specified)

PARAMETER		SYMBOL	UNIT	SL56C
Thermal Resistance	Junction to ambient	$R_{\theta J-A}$	$^\circ\text{C}/\text{W}$	50 ⁽¹⁾
	Junction to lead	$R_{\theta J-L}$	$^\circ\text{C}/\text{W}$	15 ⁽¹⁾

Note(1)

Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.6" x 0.6" (16 mm x 16 mm) copper pad areas

■ Characteristics(Typical)

FIG.1: Io-TL Curve

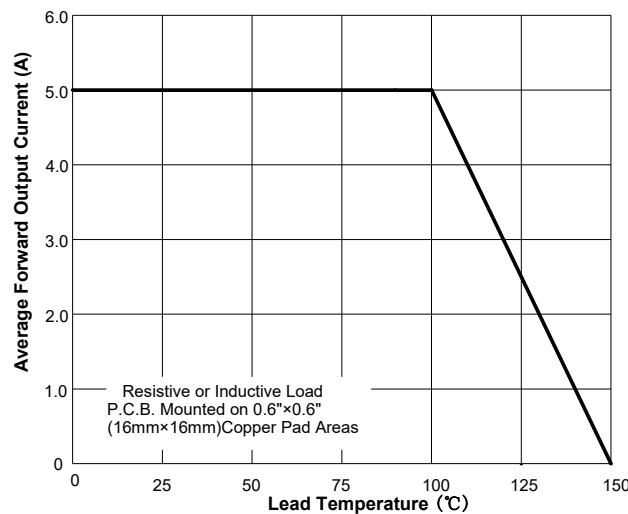


FIG.2: Forward Surge Current Capability

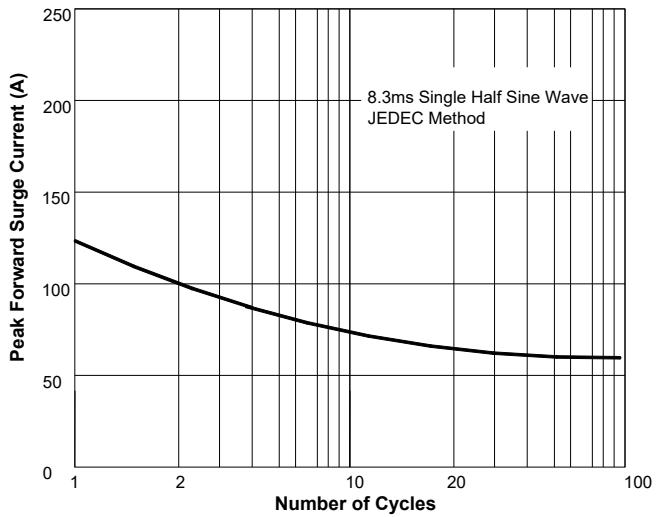


FIG.3: Forward Voltage

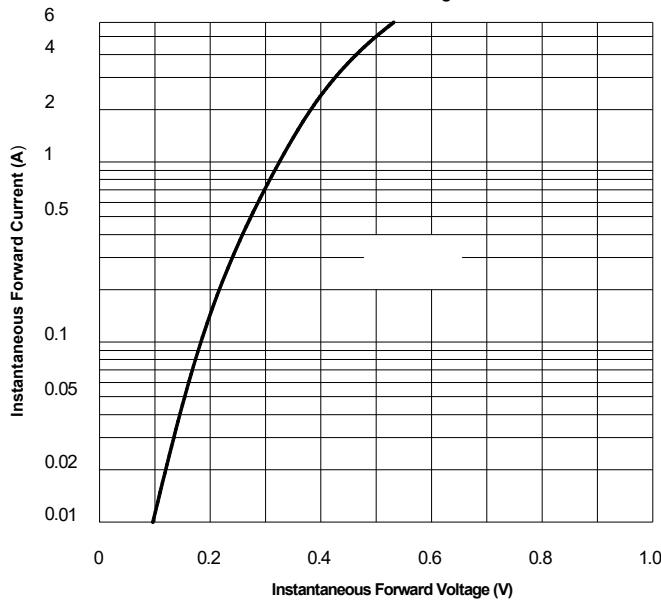


FIG4: Typical Reverse Characteristics

